

## REMARKS

The Examiner's Action mailed on April 10, 2007, has been received and its contents carefully considered. Additionally attached to this Amendment is a Request for Continued Examination (RCE).

In this Amendment, Applicant has amended the specification and claims 1, 10 and 16, and added claims 18 and 19. Claims 1-8, 10-11, 13-14, and 16-19 are pending in the application, while claims 2-8 and 11, 13-14 are withdrawn from consideration. Claims 1 and 16 have been amended to add features supported by the specification at page 19, line 11 through page 21, line 1 and Figure 2(B). New claims 18 and 19 are also supported by the specification at page 19, line 11 through page 21, line 1 and Figure 2(B). Claims 1 and 16 are the independent claims. For at least the following reasons, it is submitted that this application is in condition for allowance.

The Examiner's Action rejects claims 1 and 16 as being obvious over *Ogawa* (USP 4,418, 284) in view of *Honda* (US Pat. Pub. No. 2002/0064935). It is respectfully submitted that the invention now defined by these claims is clearly patentable over the cited references for at least the following reasons.

Amended claim 1 is directed to a semiconductor device which includes, *inter alia*, an insulating film, a light-transmitting portion, wiring patterns, post portions, a sealing layer, and external terminals. The insulating film is provided over a main surface of a semiconductor chip and surrounding side surfaces of first pads. The light-transmitting portion covers a light-receiving surface of a light-receiving element portion provided on the main surface of the semiconductor chip. The wiring patterns extend over the insulating film. The post portions are provided on and electrically connected to the

wiring patterns. The external terminals are provided on the post portions. The claim recites that the sealing layer is provided on the wiring patterns, on the insulating film, and on the surfaces of the post portions. The claim further recites that the sealing layer surrounds a side surface of the light-transmitting portion. These configurations of the claimed invention provide a constitution that is simplified in comparison with a conventional device, as supported by Applicant's specification.

This claimed invention is not disclosed, suggested, or taught by the cited references.

*Ogawa* discloses a solid-state color-image sensor with a light-shield layer covering desired portions so as to prevent noise. However, as is noted by the Examiner, *Ogawa* does not disclose or suggest the insulating film, the wiring patterns, the post portions, the sealing layer, and the external terminals, as recited in claim 1.

To overcome the above-admitted deficiencies, the Examiner relies on the teachings from *Honda*. *Honda* is directed to a semiconductor device which includes a semiconductor substrate 11, an electrode pad 12, a passivation film 13, an electrode pad bonding metal layer 21, an electroplating electrode metal layer 22, a rewiring pattern portion 24a, a metal-made circular columnar member 30, and a resin layer 27 (see *Honda*, paragraphs [0036], [0037], [0041], [0064] and [0065], Figures 2A, 2B, 2G, 4B, 4C and 4F).

The Examiner has equated the resin layer 27 disclosed by *Honda* as being equivalent of the sealing layer recited in claim 1. The resin layer 27 disclosed by *Honda* covers the circular columnar member 30 and the rewiring pattern portion 24a (see paragraph [0064], Figures 4B and 4F). However, the semiconductor device disclosed by *Honda* does not include any light-transmitting element portion, as recited in claim 1.

The resin layer 27 thus does not surround a side surface of any light-transmitting element portion, as recited in amended claim 1.

Accordingly, *Honda* fails to disclose or suggest the sealing layer surrounding a side surface of the light-transmitting element portion, as recited in claim 1. It is thus submitted that Applicant's independent claim 1 is *prima facie* patentably distinguishable over the cited references.

Claim 16 also recites a light-transmitting member, an insulating film, a wiring pattern over the insulating film, a post electrode formed on the wiring pattern, an external terminal formed on a top surface of the post electrode, and a sealing layer. The claim recites that the sealing layer is formed on the wiring pattern, on the insulating film, and on a side surface of the post electrode. The claim further recites that the sealing layer surrounds a side surface of the light-transmitting member. Because claim 16 recites above-noted features similar to those recited in claim 1, claim 16 is allowable for at least the same reasons as claim 1, as well as for the additional features recited therein.

The Examiner's Action also rejects claims 10 and 17, as being obvious over *Ogawa* in view of *Honda*, and further in view of *Lanford* (USP 5,959,358). Because *Lanford* does not overcome the above-noted deficiencies of *Ogawa* and *Honda*, and because claims 10 and 17 depend respectively from independent claims 1 and 16, it is submitted that claims 10 and 17 are *prima facie* patentably distinguishable over the cited references for at least the same reasons as independent claims 1 and 16, as well as for the additional features recited therein. It is requested that claims 10 and 17 be allowed and that this rejection be withdrawn.

AMENDMENT

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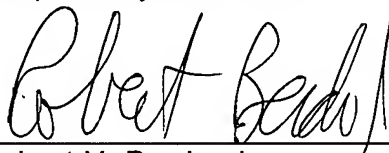
Because new claims 18 and 19 depend respectively from independent claims 16 and 1, it is submitted that these claims are *prima facie* patentably distinguishable over the cited references for at least the same reasons as independent claims 16 and 1, as well as for the additional features recited therein. It is requested that claims 18 and 19 be allowed.

It is thus submitted that this application is in condition for allowance. Such action and the passing of this case to issue are requested.

Should the Examiner feel that a conference would help to expedite the prosecution of the application, the Examiner is hereby invited to contact the undersigned counsel to arrange for such an interview.

The RCE fee of \$790 is submitted herewith as a credit card payment form PTO-2038. Should the fee be missing or in an inadequate amount, the Commissioner is hereby authorized to charge the fee or underpayment to our deposit account No. 18-0002, and is requested to notify us accordingly.

Respectfully submitted,



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Date

RHB/JJ

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